Title: CARBURIZED SILICON GATE INSULATORS FOR INTEGRATED CIRCUITS

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Please add the following new claims:

20.(New) A memory cell comprising:

- a floating gate; and
- a layer of amorphous carburized silicon between the floating gate and a substrate.
- 21.(New) The memory cell of claim 20, further comprising:
 - a source region in the substrate;
 - a drain region in the substrate;
- a channel region in the substrate between the source region and the drain region, the channel region being separated from the floating gate by the layer of amorphous carburized silicon; and
 - a control gate separated from the floating gate.
- 22.(New) The memory cell of claim 20 wherein the substrate comprises a semiconductor surface layer on an underlying insulating portion.
- 23.(New) The memory cell of claim 20 wherein the substrate comprises a doped silicon semiconductor substrate.
- 24.(New) A transistor comprising:
 - a source region in a substrate;
 - a drain region in the substrate;
 - a channel region between the source region and the drain region in the substrate; and
 - a gate separated from the channel region by a layer of amorphous carburized silicon.

25.(New)

The transistor of claim 24 wherein the gate comprises a floating gate.

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26.(New) The transistor of claim 25, further comprising a control gate separated from the floating gate

27.(New) The transistor of claim 24 wherein the substrate comprises a semiconductor surface layer on an underlying insulating portion.

The transistor of claim 24 wherein the substrate comprises a doped silicon 28.(New) semiconductor substrate.

A semiconductor device comprising: 29.(New)

a first conductive layer supported by a substrate;

a layer of amorphous carburized silicon over the first conductive layer; and

a second conductive layer over the layer of amorphous carburized silicon.

The semiconductor evice of claim 29, further comprising a source/drain 30.(New) diffusion in the substrate below the first conductive layer.

The semiconductor device of claim 29 wherein: 31.(New) the first conductive layer comprises polysilicon; and the second conductive layer comprises polysilicon.

32.(New) A memory cell comprising:

a first conductive layer supported by a substrate;

a layer of amorphous carburized silicon over the first conductive layer; and

a second conductive layer over the layer of amorphous carburized silicon.

The memory cell of claim \$2, further comprising a source/drain diffusion in the 33.(New) substrate below the first conductive layer.

AMENDMENT AND RESPONSE

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34.(New)

The memory cell of claim 32, further comprising one or more word lines

supported by the substrate

35.(New)

The memory cell of claim 32 wherein:

the first conductive layer comprises polysilicon; and

the second conductive layer comprises polysilicon.

36.(New)

A capacitor comprising:

a first conductive layer supported by a substrate;

a layer of amorphous carburized silicon over the first conductive layer; and

a second conductive layer over the layer of amorphous carburized silicon.

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37.(New) The capacitor of claim 36, further comprising a source/drain diffusion in the substrate below the first conductive layer.

Jub 1) 38.

38.(New)

The memory cell of claim 36 wherein:

the first conductive layer comprises polysilicon; and

the second conductive layer comprises polysilicon.

REMARKS

In response to the Office Action mailed April 27, 1999, the applicant respectfully requests reconsideration of the above-identified application in view of the following remarks. Claims 1-6 are pending in the application, and are rejected. Claims 3 and 4 have been amended, and new claims 20-38 have been added. No new matter has been added.

Rejection Under 35 U.S.C. 112

Claim 3 was rejected under 35 U.S.C. 112. The applicant respectfully traverses. Claim 3 has been amended to obviate the rejection.